2SD2240J

Silicon NPN epitaxial planar type

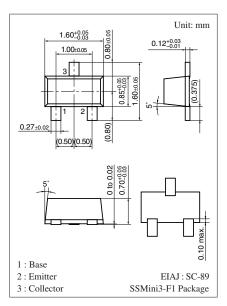
For high breakdown voltage low-noise amplification Complementary to 2SB1463J

Features

- \bullet High collector-emitter voltage (Base open) $V_{\mbox{CEO}}$
- Low noise voltage NV
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V _{CBO}	150	V				
Collector-emitter voltage (Base open)	V _{CEO}	150	V				
Emitter-base voltage (Collector open)	V _{EBO}	5	V				
Collector current	I _C	50	mA				
Peak collector current	I _{CP}	100	mA				
Collector power dissipation	P _C	125	mW				
Junction temperature	Tj	125	°C				
Storage temperature	T _{stg}	-55 to +125	°C				



Marking Symbol: P

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

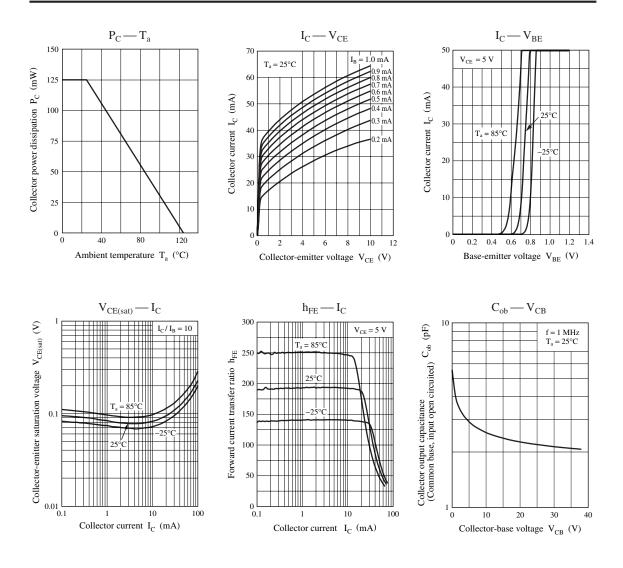
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{C} = 100 \ \mu A, I_{B} = 0$	150			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \ \mu A, \ I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 100 \text{ V}, I_E = 0$			1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$	130		330	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 30 \text{ mA}, I_{\rm B} = 3 \text{ mA}$			1	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2.3		pF
Noixe voltage	NV	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ mA}, G_V = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega$, Function = FLAT		150		mV

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S
h _{FE}	130 to 220	185 to 330

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